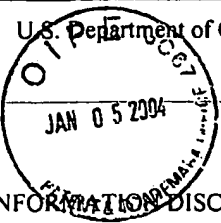


U.S. Department of Commerce, Patent and Trademark Office  INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Application No.:	09/788,273
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	Group Art Unit:	2823
	Examiner Name:	Michelle Estrada
	Confirmation No.:	6335
	Attorney Docket No.:	BOX009 US

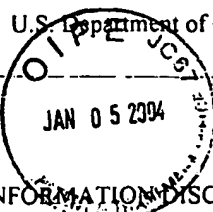
Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)								
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*Examiner Initials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
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